GOVERNMENT - INDUSTRY DATA EXCHANGE PROGRAM

PRODUCT CHANGE NOTICE

1. TITLE	2. DOCUMENT NUMBER
SMD package Lead Finish Standard	**FV5-C-18-0041**
	3. DATE **April 9, 2018**

4. MANUFACTURER AND ADDRESS	5. MANUFACTURER PART NUMBER
International Rectifier HiRel Products, Inc **205 Crawford Street** **Leominster, MA 01453**	SMD Packaged Parts
	6. BASE PART **NA**
	7. NATIONAL STOCK NUMBER (NSN) **NA**

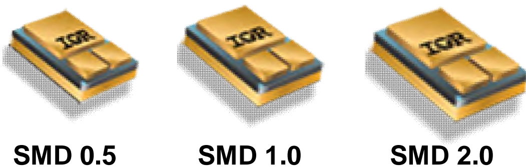
8. CAGE	9. EFFECTIVE DATE	10. GOVERNMENT NUMBER
69210	**May 15, 2018**	**NA**

11. POINT OF CONTACT	12. DRAWING NUMBER
Manufacturer's Representative or **Account Specialist (978) 534-5776**	**NA**
	13. SPECIFICATION NUMBER **MIL-PRF-19500**

14. PRODUCT CHANGE

This GIDEP PCN is to announce a change in the standard Ceramic SMD case outline lead finish. The standard lead finish for the SMD style packages will be changed from gold (Au) plating to hot solder dip (SnPb coating). International Rectifier is adding the extra solder coating step (lead finish) to its SMD packaged products as part of its finishing operations. This change applies to all quality levels (ie. COTS, TX/TXV, and S). Customers may still order gold finish as an option, however this detail will need to be specified at the point of product order.

Solder Coating Process:
SMD package leads will now be hot solder coated in 63Sn37Pb eutectic solder using an automated system. Solder coating gold-plated leads is a common practice in industry. During this process, the gold is dissolved in the solder (wave) bath which allows the solder to adhere to the base metal (nickel). The gold content of the solder bath is carefully monitored to ensure that it never exceeds 0.2% gold in order to prevent gold embrittlement in the solder joints. Solderability testing is then performed in accordance with MIL-STD-750 TM2026 requirements to ensure the packaging materials and processes used during the manufacturing operations produce a device that can be successfully soldered in the next level assembly using tin lead eutectic solder.



SMD 0.5 **SMD 1.0** **SMD 2.0**

	16. APPROVING GOVERNMENT ACTIVITY	

17. GIDEP REPRESENTATIVE	18. SIGNATURE	19. DATE
Paul Hebert		April 9, 2018

GIDEP Form 97-5